Imaps Italy Workshop
Photonic Packaging

November 4th-5th, 2025
Polytechnic University of Milan - Bovisa
Consiglio Hall, Building BL25 - Via Lambruschini, 4

Programme Day 1

9.00 **Welcome, Introduction and Pack4EU Presentation**
Luigi Calligarich, IMAPS Italy

9.30 **Introduction**
Andrea Melloni, Politecnico di Milano - Italy

10.00 **From Chip to Product: Bridging the Gap with Photonic Packaging**
Sabrine Mejri, Phix - The Netherlands

10.25 **Packaging for Emerging Photonic Enabled Quantum Applications**
Glenn George, Bay Photonics ltd - UK

10.50 Coffee break

11.20 **Innovative Laser-Assisted Bonding Technology for Photonics Packaging Applications**
Matthias Fettke, Pactech - Germany

11.45 **A Versatile and Unified Software Platform for Precise Photonics Packaging Control**
Gabriele Galeazzi, Visiorobotics - Italy

12.10 **Adhesives for highly efficient optical coupling of Photonic Integrated Circuits**
Alexander Hartwig, DELO - Germany

12.35 *Lunch (free time)*

14.15 **Photonic Glass Core Substrates for Data Centers and Optical Computing**
Julian Schwietering, Fraunhofer Institute for Reliability and Microintegration IZM - Germany

14.40 **Photonic Wire Bonds and Facet-Attached Micro-Lenses: Enabling Scalable Integration of Lasers and PICs** *Laura Horan, Vanguard Automation GmbH - Germany*

15.05 **Glass micro-components for fiber connectivity in co-packaged optics and quantum photonics**
Rolando Ferrini, FemtoPrint - Switzerland

15.30 Coffee break

16.00 ***Metallic Interconnects for Co-Packaged Photonic Integrated Circuits***
Andrew Meek, Senko - UK

16.25 ***Optical PCBs as a Scalable Platform for High-Density Photonic Packaging***
Nikolaus Flöry, Vario Optics - Switzerland

16.50 ***Single chip-DWDM External laser source for Co-packaged optics***
Sylvie Menezo, SCINTIL Photonics

17.20 *First day closing*

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Programme Day 2

9.00 **Welcome**
Luigi Calligarich, IMAPS Italy

9.15 ***Advanced Packaging enabling Photonics Module integration***
Stéphane Bernabé, CEA Leti - France

9.40 **Advanced Photonics Packaging – a key aspect for the ecosystem**
Giorgio Cazzaniga, Jabil - Italy

10.00 **AI-driven packaging strategies, including silicon photonics integration for high-performance computing and Network system**
Roberto Dossi, ASE - Italy

10.25 *Coffee break*

10.50 **Thin film deposition developments for Co-Packed Optics as next Heterogeneous Integration Evolution Step**
Ewald Strolz, Evatec - Italy

11.20 **Integrated Photonic Coupling Interfaces - Expectations and Challenges**
Galina Georgieva, Axinora - Bulgaria

11.45 **EPIQUS – Electronic-photonic integrated quantum simulator platform**
Mher Ghulinyan, FBK - Italy

12.10 Lunch (free time)

13.50 **Industrial Packaging of photonic devices for telecom and DCI applications**
Victor Guja, Nokia - Italy

14.15 ***Packaging Techniques for High-Speed TFLN devices***
Alberto Rampulla, AFR - Italy

14.50 **Free Space Optical communication for 5GA and 6G: Challenges, Opportunities, and Future Directions**
Angelo Milani, Huawei - Italy

15.05 *Coffee break*

15.35 **Introduction to multilayer glass interposers fabrication, suitable for Co-Packaged Optics and Quantum processor applications.**
Giovanni Del Rosso, Phospack - Finland

16.00 ***Reliability Considerations on LCP Air-Cavity Packages for Photonics Integrated Circuits (PICs)***
Marco H. Koelink, RJR Technologies - USA

16.25 *Next events /closing of workshop*

Information

The conference will be held in English language in presence, for up to 100 people.
Access is free and subject to availability, mandatory registration
CLICK HERE OR SCAN THE QR CODE

Contacts
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